

FIG.1

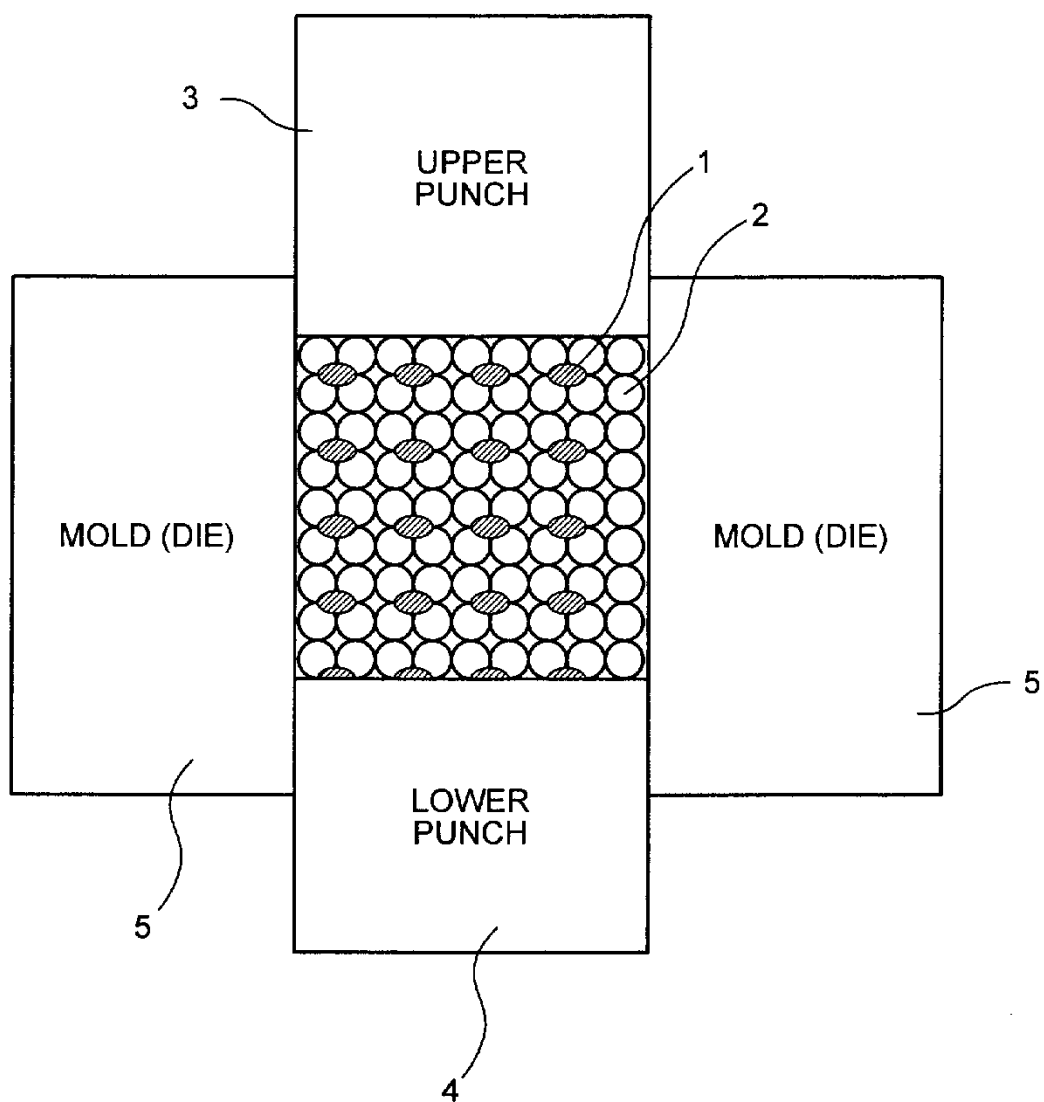


FIG.2

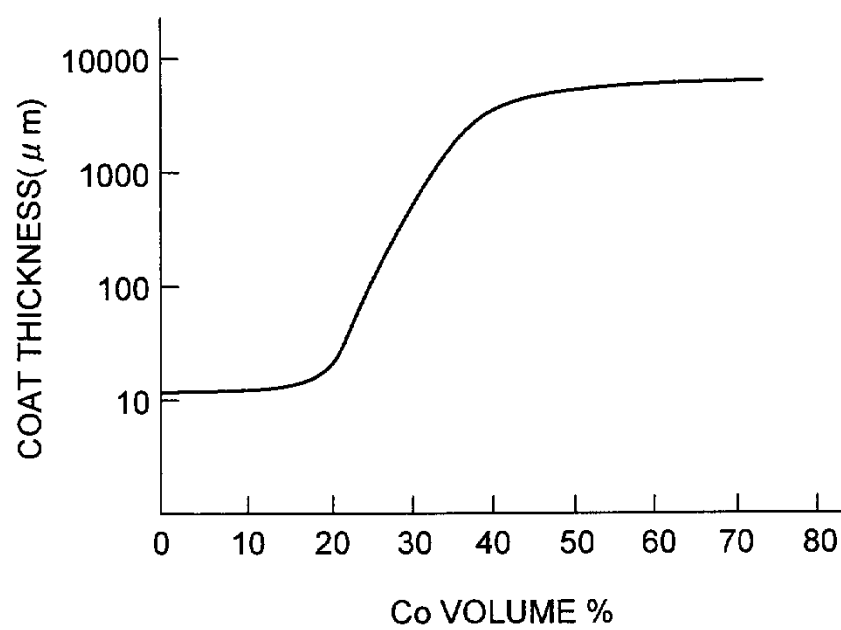


FIG.3A

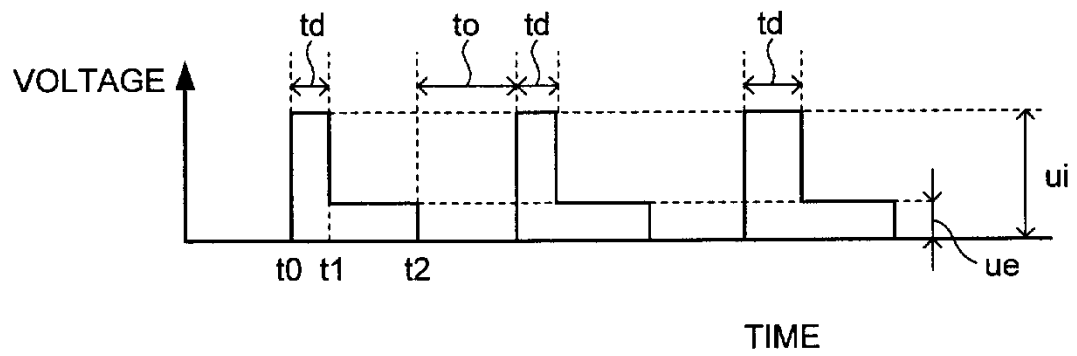


FIG.3B

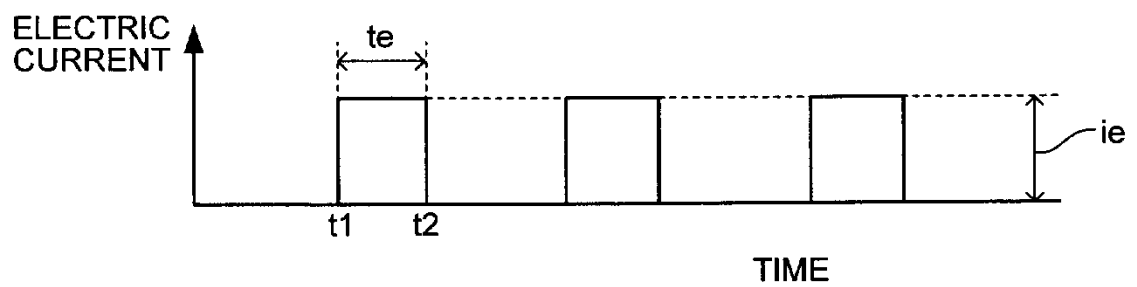


FIG.4

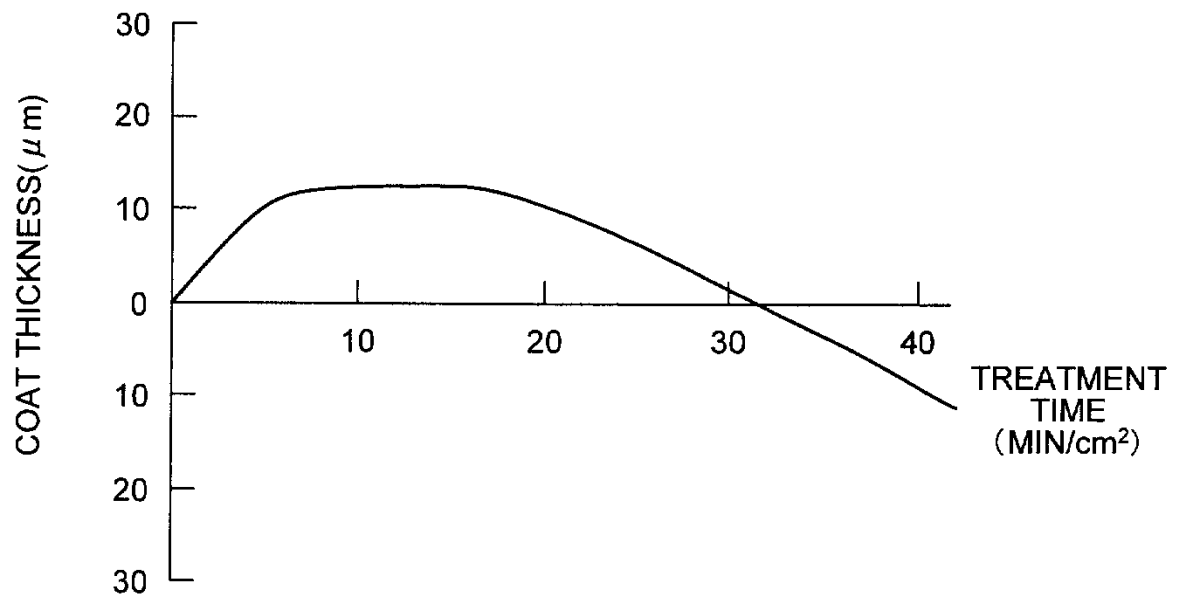


FIG.5



FIG.6

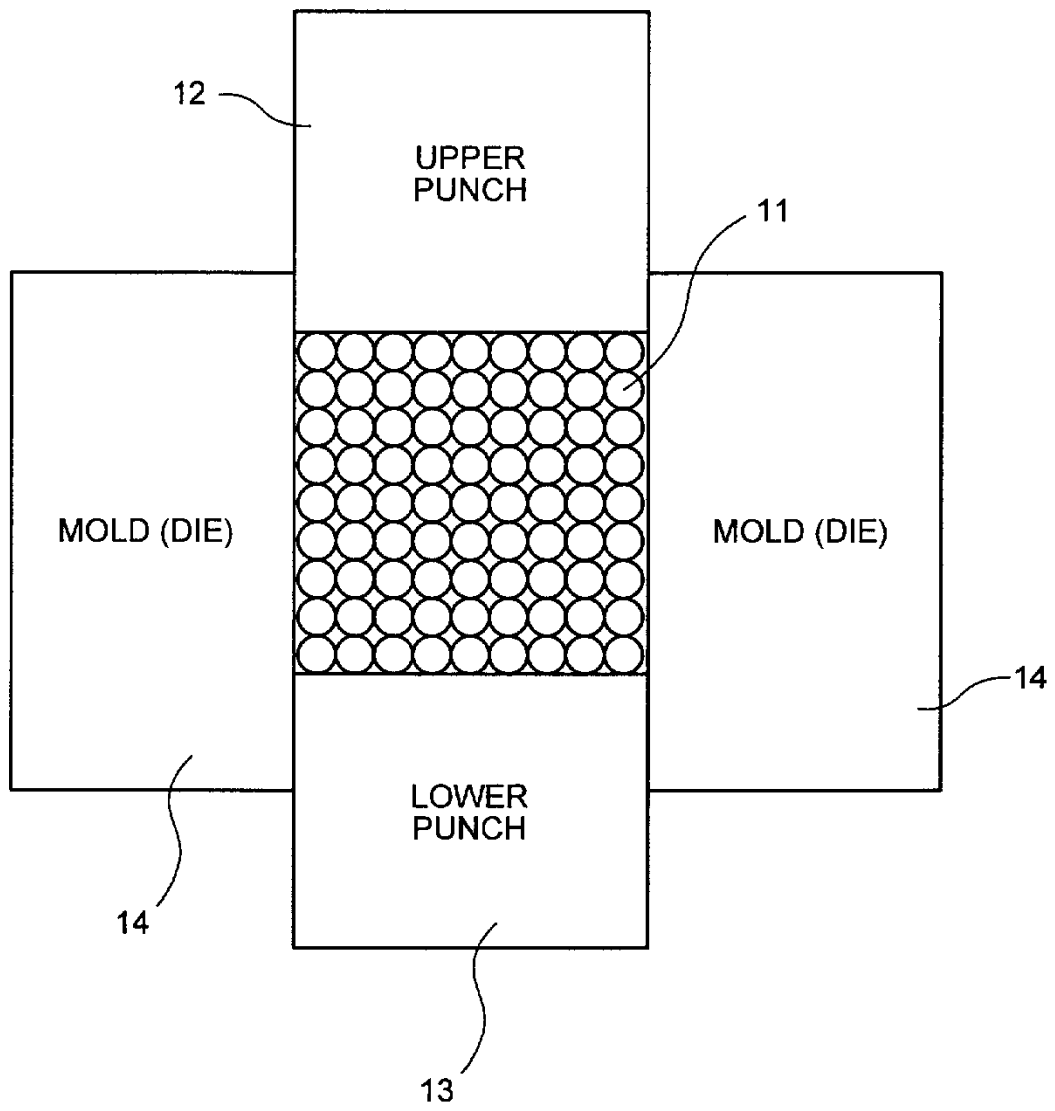


FIG.7A

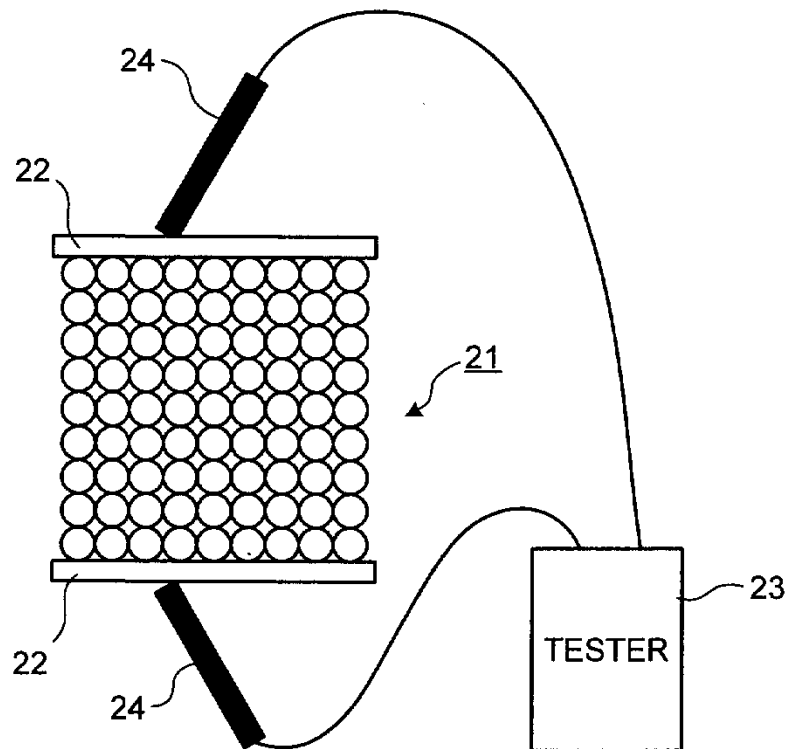


FIG.7B

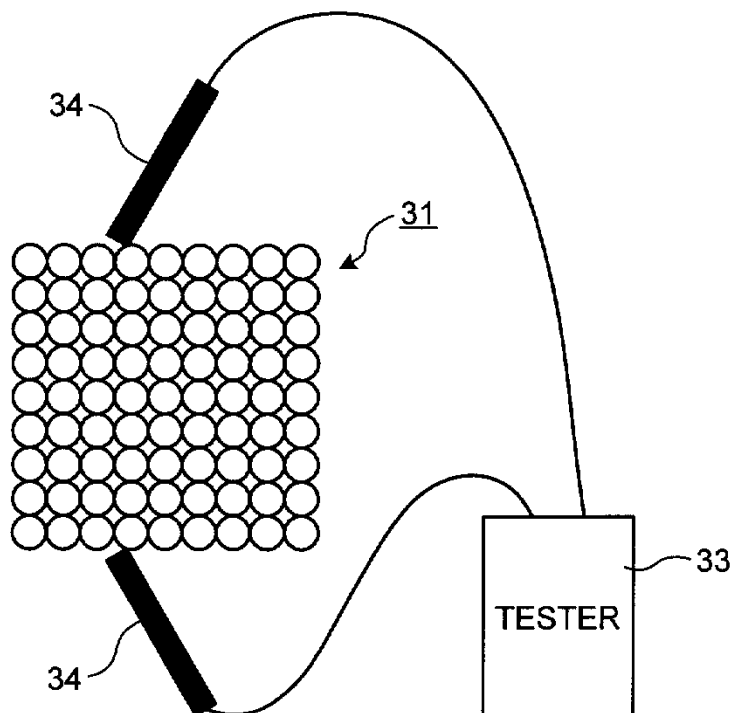


FIG.8

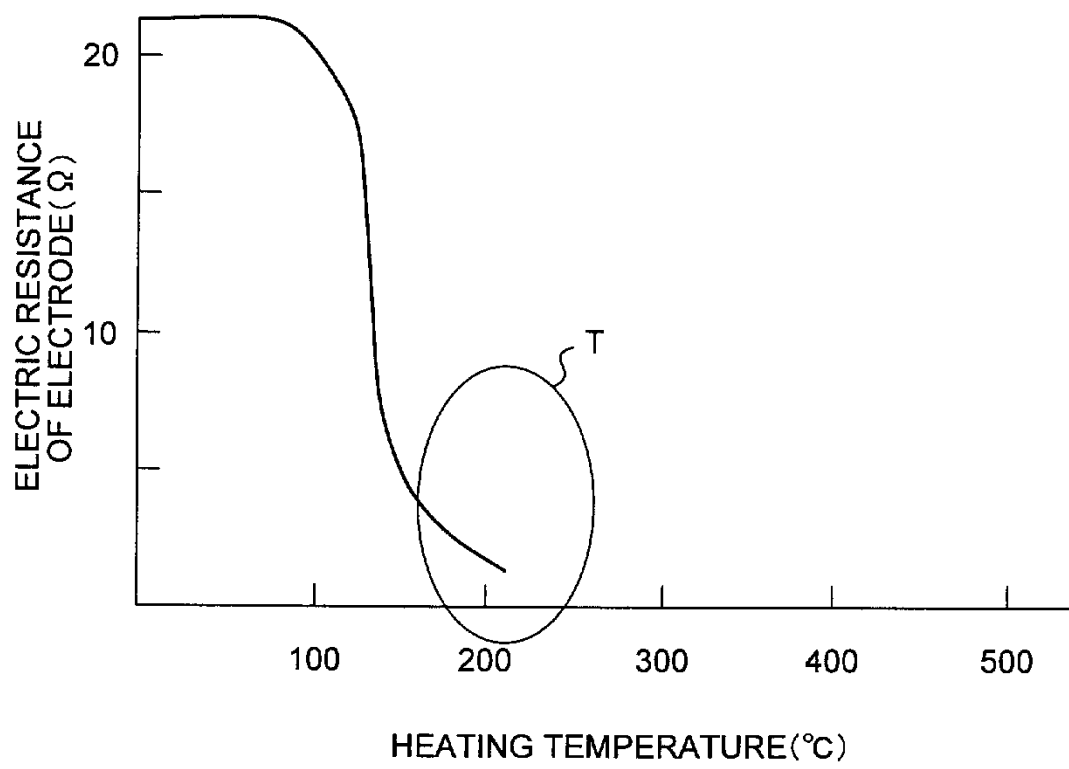


FIG. 9

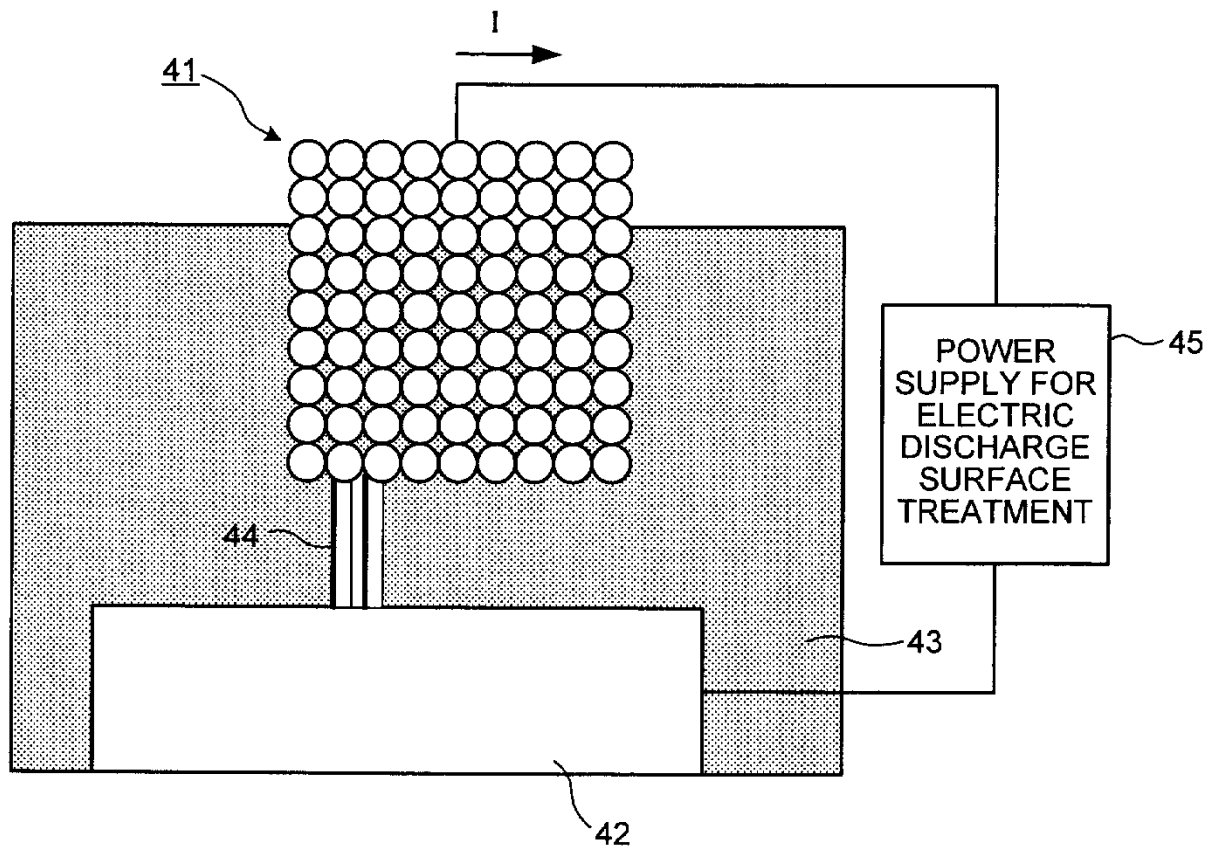


FIG.10

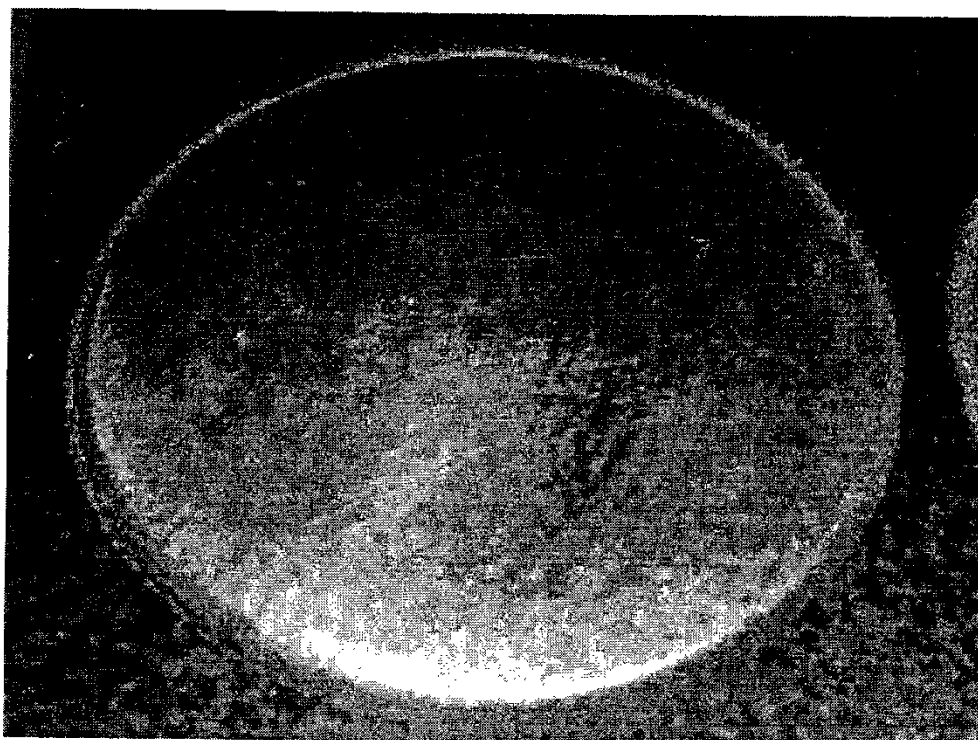


FIG.11

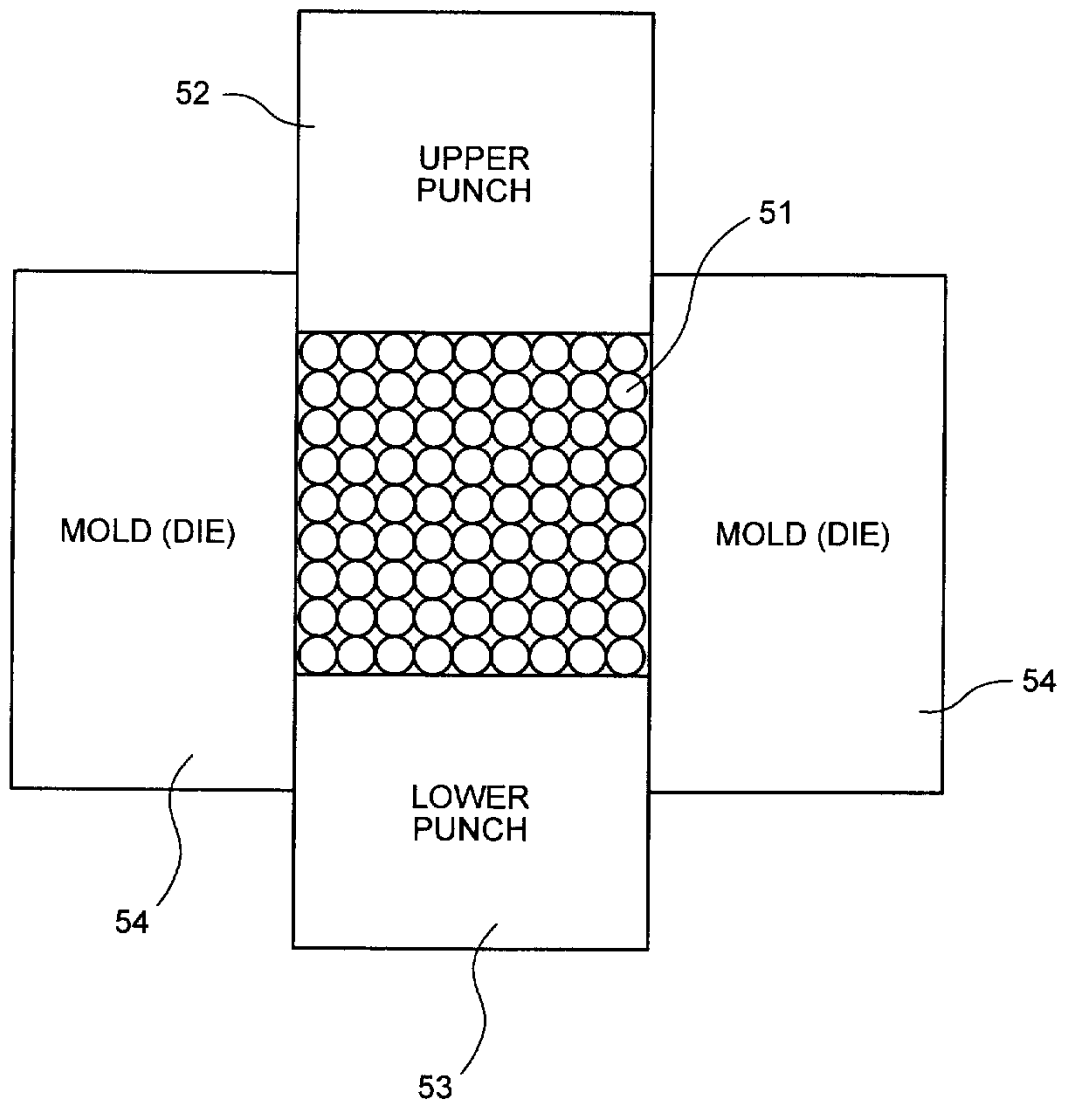


FIG.12

PULSE WIDTH (μs) AVERAGE GRAIN DIAMETER(μm)	~50	5~100	50~500	500~
~3	DENSE THICK FILM CAN BE FORMED	THICK FILM CAN BE FORMED BUT THE FILM IS POROUS	IT IS DIFFICULT TO FORM THICK FILM	TREATMENT IS UNSTABLE (E.G., SHORT CIRCUIT OCCURS)
2~6	THICK FILM CAN BE FORMED BUT THE FILM IS POROUS	DENSE THICK FILM CAN BE FORMED	THICK FILM CAN BE FORMED BUT THE FILM IS POROUS	TREATMENT IS UNSTABLE (E.G., SHORT CIRCUIT OCCURS)
6~10	COARSE POWDER ONLY DEPOSITS ON WORK	THICK FILM CAN BE FORMED BUT THE FILM IS POROUS	DENSE THICK FILM CAN BE FORMED	THICK FILM CAN BE FORMED BUT THE FILM IS POROUS (TREATMENT IS UNSTABLE WHEN PULSE WIDTH BECOMES LONGER)

FIG.13

